

SMT Pick And Place Machines Sony SI-F209

Basic Information

Place of Origin: Japan
Brand Name: Sony
Model Number: SI-F209
Minimum Order Quantity: 1 PCS

Price: USD+negotiable+pcs
Packaging Details: 1350*1850*1650mm

Delivery Time: 1-7 daysPayment Terms: T/T

Supply Ability: 1+pcs+per days



Product Specification

Model: Sony SI-F209

• Substrate Size: 50mm*50mm-460mm*360mm

Substrate Thickness: 0.5mmto2.6mm
 Number Of Mounting Heads: 1 Head 6 Nozzles

neaus

• Mounting Range: 2012(0804)-32mmlC

Component Height: Max 7mm Mobile Camera Fixed Camera

25mm

• Mounting Speed: 0.49sec(7350CPH)

Mounting Accuracy: 60um (CPK1.0 Or Above) Chip)
 Power Supply: AC3-phase 200V±10% 50/60HZ

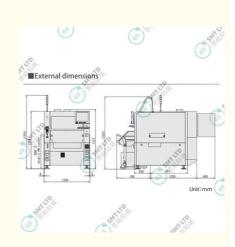
• Power Consumption: 2.3kw

• Gas Consumption: 0.49MPA 100L/min

• Appearance Size: 1220mm*1700mm*1573mm

• Weight: 1800KG

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Product Description

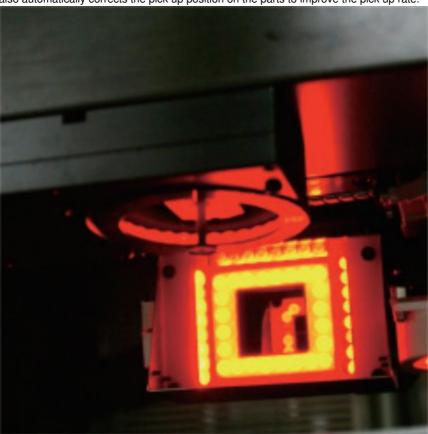
Description:

Enhance your PCB assembly with the Sony SI-F209, a cutting-edge SMT mounter renowned for its precision and high-speed capabilities. With a robust modular design that allows for rapid reconfiguration, this machine is an ideal solution for electronics manufacturers seeking to maximize productivity and reduce placement costs. It boasts an adaptable feeder system capable of handling a diverse array of components, ensuring seamless integration into any SMT line. The SI-F209's advanced vision system guarantees exact alignment and placement, driving efficiency even for complex boards. Rely on Sony's innovation to meet the demanding standards of modern SMT production with this versatile mounter.

Electronic Part Mounter SI-F209:

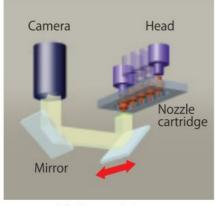
1. Supports large, odd-shaped parts

The unit is equipped with a multifunction head that is capable of mounting parts ranging from size 2012 to φ150mm. The unit also automatically corrects the pick up position on the parts to improve the pick up rate.

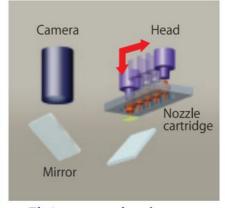


2.Reduces loss in tact time

To increase productivity, the unit features flying vision and flying nozzle change functions, which respectively perform parts recognition and nozzle changes, while the head is in motion after picking up or placing parts.



Flying vision



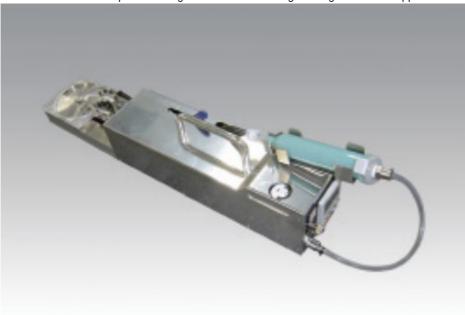
Flying nozzle change

3.Coplanarity system*

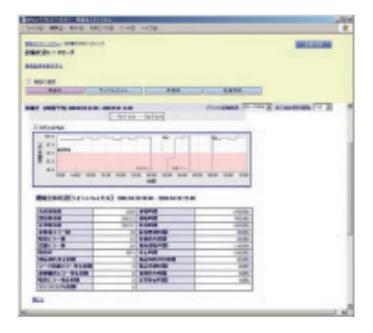
This system inspects leads and solder balls of the large parts such as QFP and BGA.



4.Dip Unit*
This is a flux and solder paste coating unit for POP mounting. Coating material is supplied automatically.



5.PDX(Product Explorer)*
Receives and distributes production data and performs device management at will. Improves your productivity, traceability and quality levels through remote machine control.



6.CPS Pro 4*

This software optimizes the layout of nozzles and parts supply on all the SI series. Equipped with the same GUI as the unit's display, it is even easier to use.

